



# SOT619-16

HVQFN48, plastic, thermal enhanced very thin quad flatpack; no leads; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 0.85 mm body

22 January 2019

Package information

## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN48
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	07-01-2016
<b>Manufacturer package code</b>	98ASA00343D

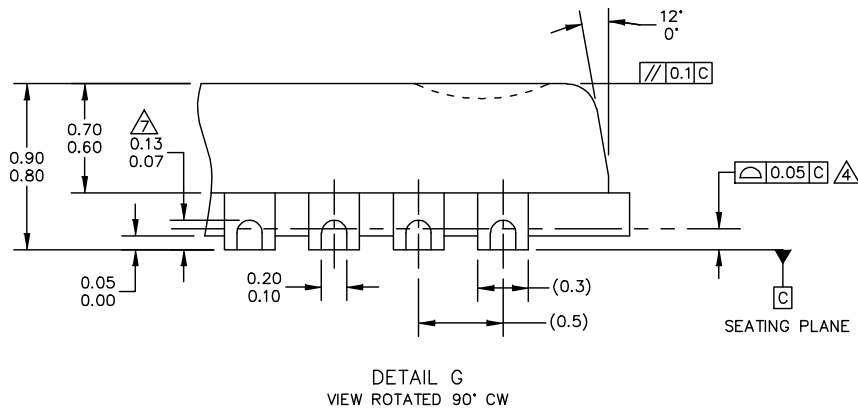
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	7	-	mm
package width	-	7	-	mm
package height	-	0.85	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	48	-	





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TITLE: THERMALLY ENHANCED PUNCH QUAD FLAT NON-LEADED (QFN) PACKAGE WITH WETTABLE FLANKS 48 TERMINAL, 7 X 7 X 0.85, 0.5 PITCH		DOCUMENT NO: 98ASA00343D	REV: B
		STANDARD: NON-JEDEC	
		SOT619-16	07 JAN 2016

Figure 2. Package outline dt1 HVQFN48 (SOT619-16)

HVQFN48, plastic, thermal enhanced very thin quad flatpack; no leads; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 0.85 mm body

3 Soldering

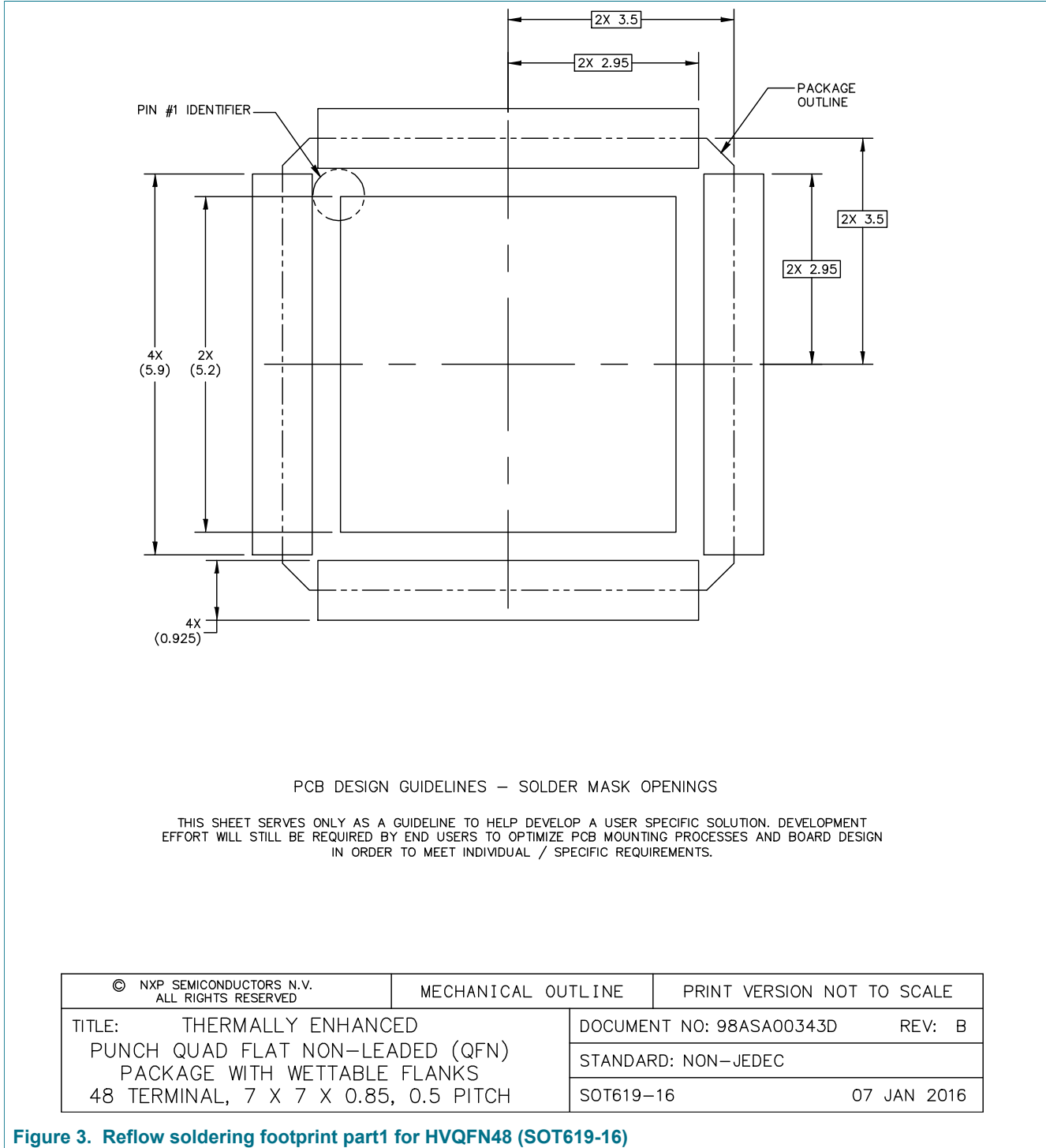
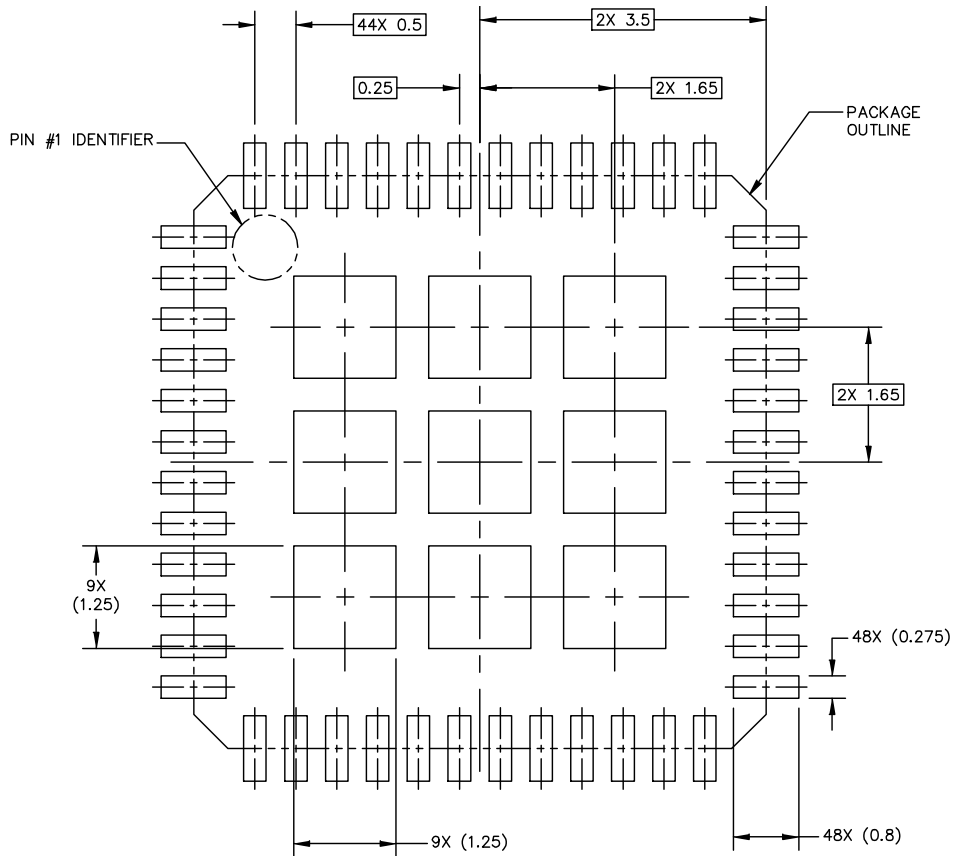


Figure 3. Reflow soldering footprint part1 for HVQFN48 (SOT619-16)

HVQFN48, plastic, thermal enhanced very thin quad flatpack; no leads; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 0.85 mm body



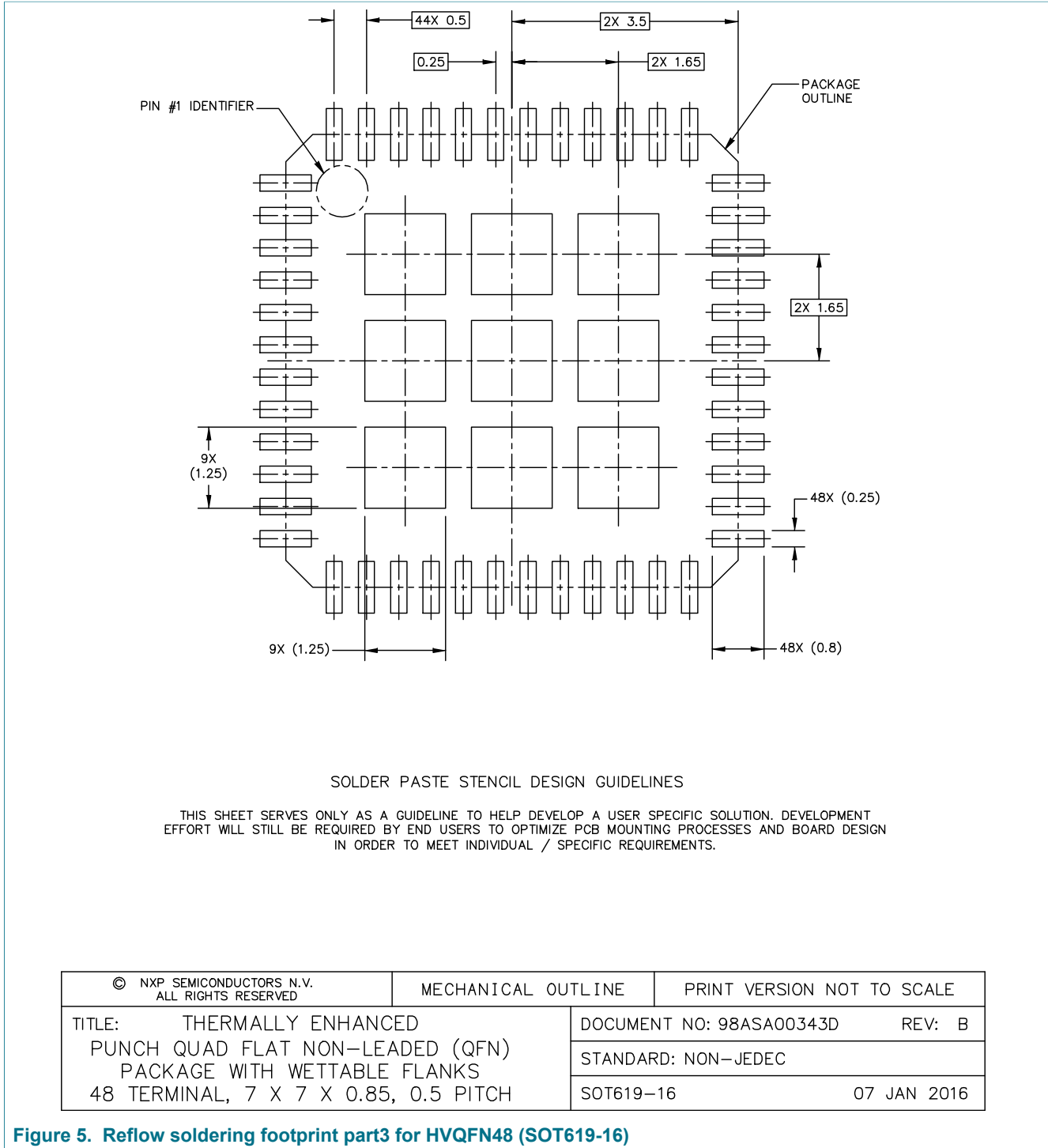
PCB CU GUIDELINES – I/O PADS & SOLDERABLE AREAS

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL / SPECIFIC REQUIREMENTS.

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	STANDARD: NON-JEDEC	
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Figure 4. Reflow soldering footprint part2 for HVQFN48 (SOT619-16)

HVQFN48, plastic, thermal enhanced very thin quad flatpack; no leads; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 0.85 mm body



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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS NON JEDEC REGISTERED PACKAGE.
- ⚠ COPLANARITY APPLIES TO LEADS, CORNER LEADS AND DIE ATTACH FLAG.
5. MIN METAL GAP BETWEEN TERMINAL AND DIE PADDLE SHALL BE 0.25MM.
- ⚠ THIS DIMENSION APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25MM FROM TERMINAL TIP.
- ⚠ THIS DIMENSION APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.02MM AND PACKAGE CUTTING LINE.

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Figure 6. Package outline note HVQFN48 (SOT619-16)

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## 4 Legal information

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**Contents**

---

1 Package summary .....1  
2 Package outline .....2  
3 Soldering .....4  
4 Legal information .....8